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- Qualified for Automotive Applications
- Inputs Are TTL-Voltage Compatible
- Buffered Inputs
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design

| I     |   | PACK<br>OP VI |    |                           |
|-------|---|---------------|----|---------------------------|
| 1A [  | 1 | υ             | 14 |                           |
| 1B [  | 2 |               | 13 | ] V <sub>CC</sub><br>] 4B |
| 1Y [  | 3 |               | 12 | ] 4A                      |
| 2A [  | 4 |               | 11 | ] 4Y                      |
| 2B [  | 5 |               | 10 | ] 3B                      |
| 2Y [  | 6 |               | 9  | ] 3A                      |
| GND [ | 7 |               | 8  | ] 3Y                      |
|       |   |               |    | I                         |

#### description/ordering information

The CD74ACT32 is a quadruple 2-input positive-OR gate. This device performs the Boolean function  $Y = \overline{\overline{A \bullet B}}$  or Y = A + B in positive logic.

#### **ORDERING INFORMATION<sup>†</sup>**

| T <sub>A</sub>  | PACKAGE <sup>‡</sup>   |  | ORDERABLE<br>PART NUMBER | TOP-SIDE<br>MARKING |  |  |  |
|---|------------------------|--|--------------------------|---------------------|--|--|--|
| –40°C to 125°C  | SOIC – M Tape and reel |  | CD74ACT32QM96Q1          | ACT32Q              |  |  |  |
| the most surrout realises and and rise information, and the Declars Orthop Addredum at the and of |                        |  |                          |                     |  |  |  |

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

| FUNCTION TABLE<br>(each gate) |   |   |  |  |  |
|-------------------------------|---|---|--|--|--|
| INPUTS OUTPUT                 |   |   |  |  |  |
| Α                             | В | Y |  |  |  |
| Н                             | Х | Н |  |  |  |
| Х                             | Н | н |  |  |  |
| L                             | L | L |  |  |  |

#### logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

| Supply voltage range, V <sub>CC</sub>   | –0.5 V to 6 V  |
|---|----------------|
| Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)                            | ±20 mA         |
| Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1) | ±50 mA         |
| Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$   | ±50 mA         |
| Continuous current through V <sub>CC</sub> or GND   | ±100 mA        |
| Package thermal impedance, $\theta_{JA}$ (see Note 2)   |                |
| Storage temperature range, T <sub>stg</sub>   | –65°C to 150°C |

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

|                     |                                    | T <sub>A</sub> = 25°C |          | –40°(<br>125 | UNIT     |      |
|---------------------|------------------------------------|-----------------------|----------|--------------|----------|------|
|                     |                                    | MIN                   | MAX      | MIN          | MAX      |      |
| V <sub>CC</sub>     | Supply voltage                     | 4.5                   | 5.5      | 4.5          | 5.5      | V    |
| V <sub>IH</sub>     | High-level input voltage           | 2                     |          | 2            |          | V    |
| VIL                 | Low-level input voltage            |                       | 0.8      |              | 0.8      | V    |
| VI                  | Input voltage                      | 0                     | $V_{CC}$ | 0            | $V_{CC}$ | V    |
| Vo                  | Output voltage                     | 0                     | $V_{CC}$ | 0            | $V_{CC}$ | V    |
| I <sub>OH</sub>     | High-level output current          |                       | -24      |              | -24      | mA   |
| I <sub>OL</sub>     | Low-level output current           |                       | 24       |              | 24       | mA   |
| $\Delta t/\Delta v$ | Input transition rise or fall rate |                       | 10       |              | 10       | ns/V |

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                  | TEST CONDITIONS                     | V <sub>CC</sub>                     | T <sub>A</sub> = 25°C |      | –40°C to<br>125°C |      | UNIT |    |
|----------------------------|-------------------------------------|-------------------------------------|-----------------------|------|-------------------|------|------|----|
|                            |                                     |                                     |                       | MIN  | MAX               | MIN  | MAX  |    |
|                            |                                     | I <sub>OH</sub> = -50 μA            | 4.5 V                 | 4.4  |                   | 4.4  |      |    |
| V <sub>OH</sub>            | $V_{I} = V_{IH} \text{ or } V_{IL}$ | $I_{OH} = -24 \text{ mA}$           | 4.5 V                 | 3.94 |                   | 3.7  |      | V  |
|                            |                                     | $I_{OH} = -50 \text{ mA}^{\dagger}$ | 5.5 V                 |      |                   | 3.85 |      |    |
|                            | $V_{I} = V_{IH} \text{ or } V_{IL}$ | I <sub>OL</sub> = 50 μA             | 4.5 V                 |      | 0.1               |      | 0.1  | V  |
| V <sub>OL</sub>            |                                     | I <sub>OL</sub> = 24 mA             | 4.5 V                 |      | 0.36              |      | 0.5  |    |
|                            |                                     | $I_{OL} = 50 \text{ mA}^{\dagger}$  | 5.5 V                 |      |                   |      | 1.65 |    |
| l <sub>l</sub>             | $V_I = V_{CC}$ or GND               |                                     | 5.5 V                 |      | ±0.1              |      | ±1   | μA |
| I <sub>CC</sub>            | $V_I = V_{CC}$ or GND,              | I <sub>O</sub> = 0                  | 5.5 V                 |      | 4                 |      | 80   | μA |
| $\Delta I_{CC}^{\ddagger}$ | $V_{I} = V_{CC} - 2.1 V$            |                                     | 4.5 V to<br>5.5 V     |      | 2.4               |      | 3    | mA |
| Ci                         |                                     |                                     |                       |      | 10                |      | 10   | pF |

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75-Ω transmission-line drive capability at 125°C.

<sup>‡</sup> Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

#### ACT INPUT LOAD TABLE

| INPUT | UNIT LOAD |
|-------|-----------|
| All   | 0.42      |

Unit load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

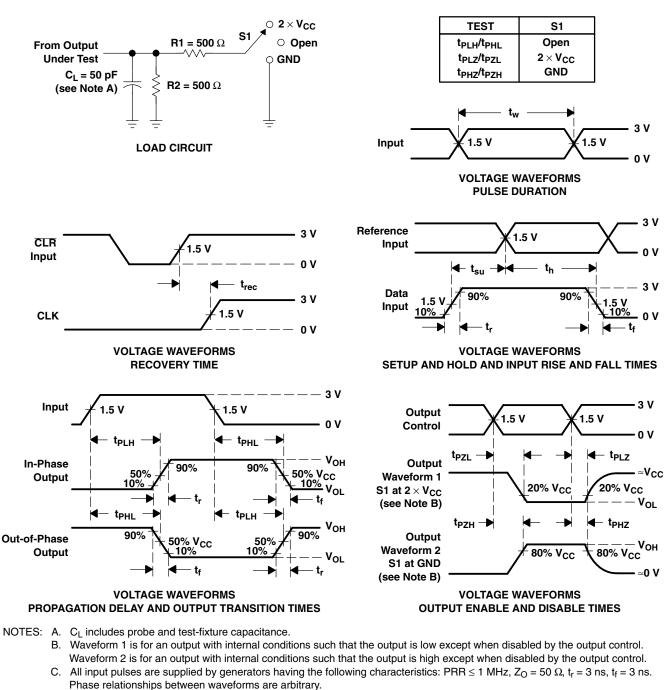
| PARAMETER        | FROM    | TO       | –40°(<br>125 | UNIT |    |
|------------------|---------|----------|--------------|------|----|
|                  | (INPUT) | (OUTPUT) | MIN          | MAX  |    |
| t <sub>PLH</sub> | A or B  | X        | 3            | 12.1 | 20 |
| t <sub>PHL</sub> | AOIB    | Ţ        | 3            | 12.1 | ns |

### operating characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

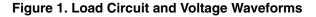
|                 | PARAMETER                     | ТҮР | UNIT |
|-----------------|-------------------------------|-----|------|
| C <sub>pd</sub> | Power dissipation capacitance | 47  | pF   |



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- D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G.  $t_{PZI}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- I. All parameters and waveforms are not applicable to all devices.







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#### PACKAGING INFORMATION

| Orderable Device  | Status <sup>(1)</sup> | Package<br>Type | Package<br>Drawing | Pins Pa | ackage<br>Qty | Eco Plan <sup>(2)</sup>    | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|-------------------|-----------------------|-----------------|--------------------|---------|---------------|----------------------------|------------------|------------------------------|
| CD74ACT32QM96G4Q1 | ACTIVE                | SOIC            | D                  | 14      | 2500          | Green (RoHS &<br>no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD74ACT32QM96Q1   | ACTIVE                | SOIC            | D                  | 14      | 2500          | Green (RoHS &<br>no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD74ACT32QPWRQ1   | OBSOLETE              | TSSOP           | PW                 | 14      |               | TBD                        | Call TI          | Call TI                      |

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Addendum-Page 1

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#### OTHER QUALIFIED VERSIONS OF CD74ACT32-Q1 :

• Catalog: CD74ACT32

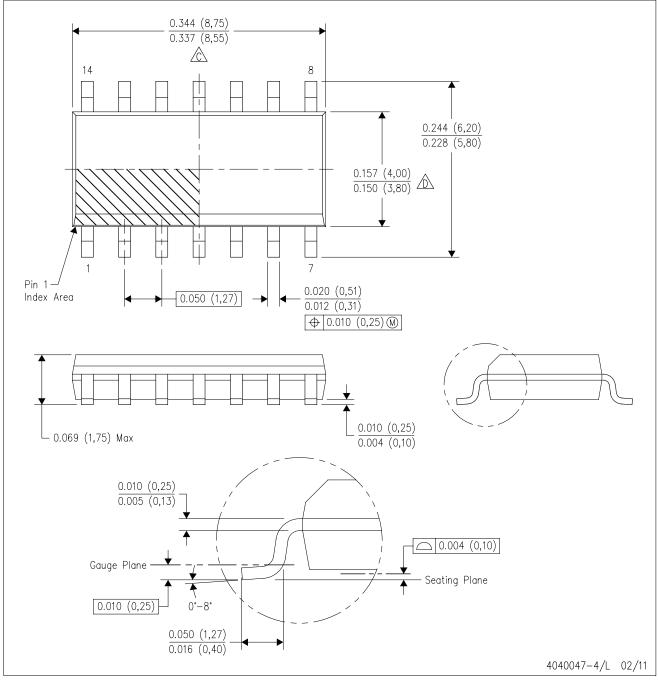
• Military: CD54ACT32

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

D (R-PDSO-G14)

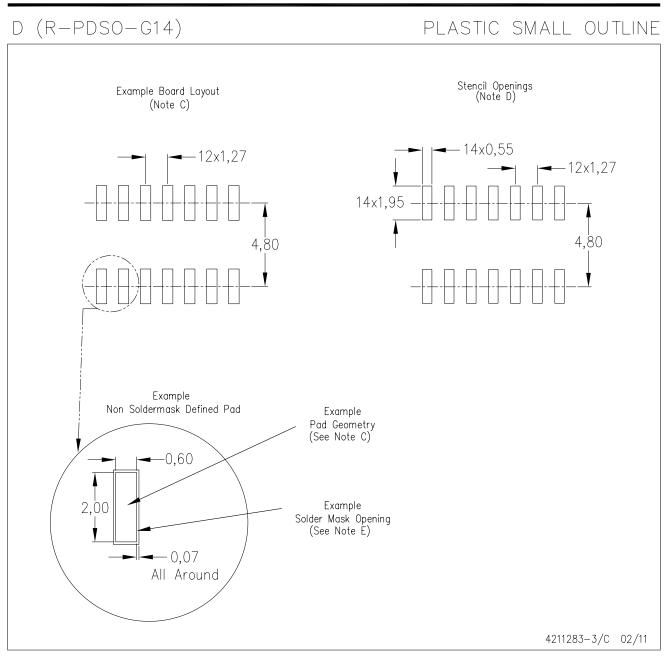
PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





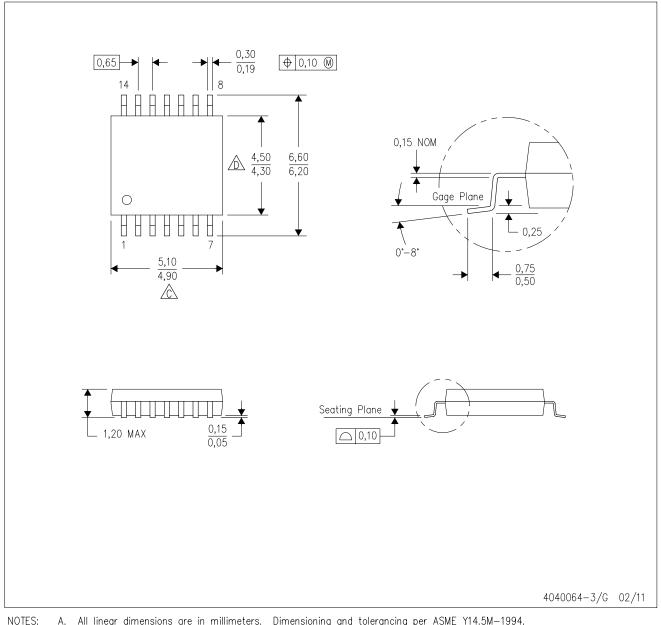
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



Α. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. Ŗ. This drawing is subject to change without notice.

 $\triangle$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



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